Chip Bead For EMI Suppression

CIB/CIM10 Series (1608/ EIA 0603)

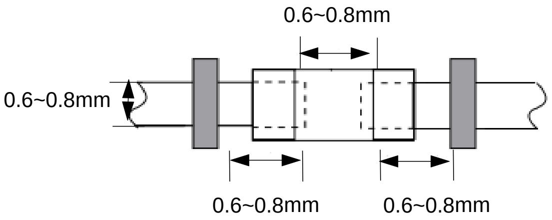
APPLICATION

High frequency EMI prevention application to computers, printers, VCRs, TVs and mobile phones.

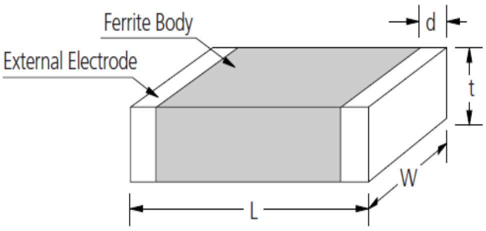
FEATURES

- Perfect shape for automatic mounting, with no directionality.
- Excellent solderability and high heat resistance for either flow or reflow soldering
- Monolithic inorganic material construction for high reliability
- Closed magnetic circuit configuration avoids crosstalk and is suitable for high density PCBs.

RECOMMENDED LAND PATTERN



DIMENSION



Type	Dimension [mm]			
	L	W	t	d
10	1.6±0.15	0.8±0.15	0.8±0.15	0.3±0.2

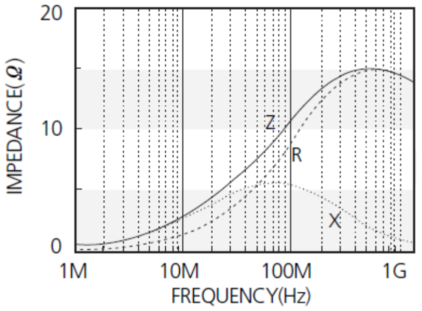
DESCRIPTION

Part no.	Thickness (mm)	Impedance (Ω)±25%@100MHz	DC Resistance (Ω) Max.	Rated Current (mA) Max.
CIB10P100	0.8±0.15	10	0.05	1000
CIB10P220	0.8±0.15	22	0.05	1500
CIB10P260	0.8±0.15	26	0.08	1000
CIB10P300	0.8±0.15	30	0.08	1000
CIB10P330	0.8±0.15	33	0.08	1000
CIM10U800	0.8±0.15	80	0.10	600
CIM10U121	0.8±0.15	120	0.15	500
CIM10U221	0.8±0.15	220	0.25	400
CIM10U241	0.8±0.15	240	0.25	400
CIM10U301	0.8±0.15	300	0.30	400
CIM10U471	0.8±0.15	470	0.35	300
CIM10U601	0.8±0.15	600	0.38	500
CIM10U102	0.8±0.15	1000	0.50	400
CIM10U202	0.8±0.15	2000(at 70MHz)	1.20	200
CIB10J300	0.8±0.15	30	0.10	1000
CIM10J400	0.8±0.15	40	0.12	600
CIM10J470	0.8±0.15	47	0.12	600
CIM10J600	0.8±0.15	60	0.12	600
CIM10J750	0.8±0.15	75	0.15	550
CIM10J800	0.8±0.15	80	0.15	550
CIM10J121	0.8±0.15	120	0.20	500
CIM10J151	0.8±0.15	150	0.20	400
CIM10J221	0.8±0.15	220	0.30	400
CIM10J241	0.8±0.15	240	0.30	400

Part no.	Thickness (mm)	Impedance (Ω)±25%@100MHz	DC Resistance (Ω) Max.	Rated Current (mA) Max.
CIM10J301	0.8±0.15	300	0.35	400
CIM10J471	0.8±0.15	470	0.35	300
CIM10J601	0.8±0.15	600	0.45	300
CIM10J751	0.8±0.15	750	0.50	300
CIM10J102	0.8±0.15	1000	0.60	250
CIM10J152	0.8±0.15	1500	0.70	250
CIM10J252	0.8±0.15	2500	1.50	200
CIM10K152	0.8±0.15	1500	0.80	250
CIM10K202	0.8±0.15	2000	1.00	200
CIM10K252	0.8±0.15	2500	1.20	200
CIM10N700	0.8±0.15	70	0.30	500
CIM10N121	0.8±0.15	120	0.45	400
CIM10N241	0.8±0.15	240	0.60	300
CIM10F470	0.8±0.15	47	0.25	550
CIM10F600	0.8±0.15	60	0.25	550
CIM10F121	0.8±0.15	120	0.30	500
CIM10F331	0.8±0.15	330	0.58	400
CIM10F471	0.8±0.15	470	0.85	300

CHARACTERISTIC DATA

CIB10P100



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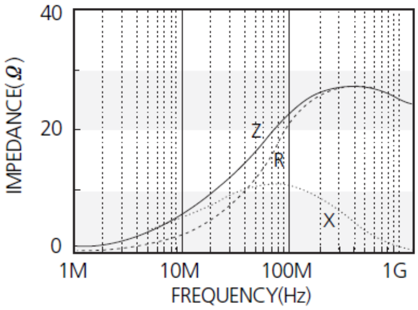

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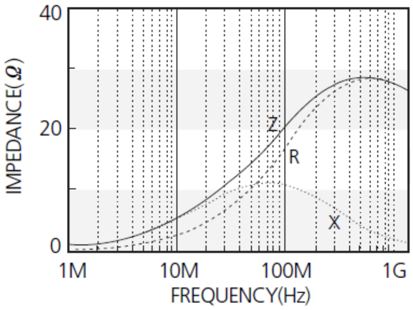

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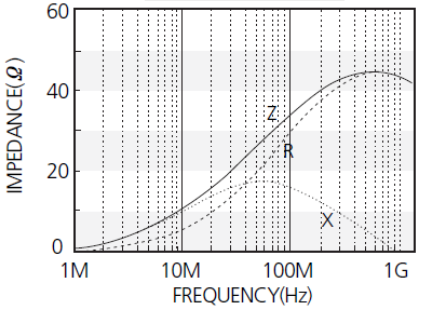

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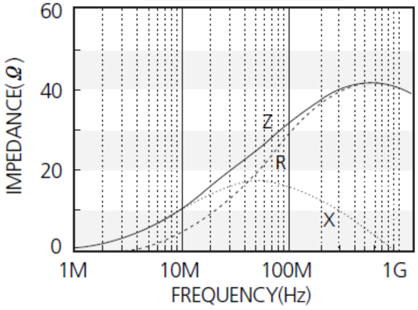

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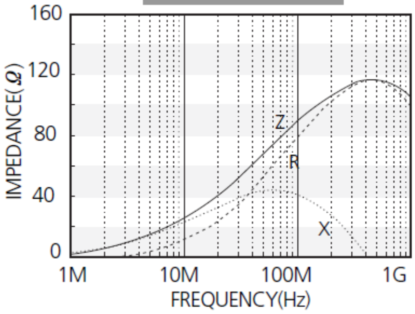

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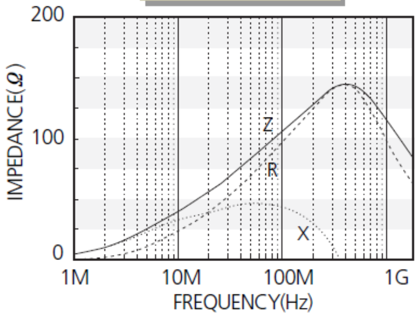

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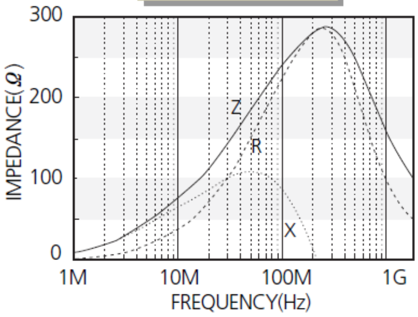

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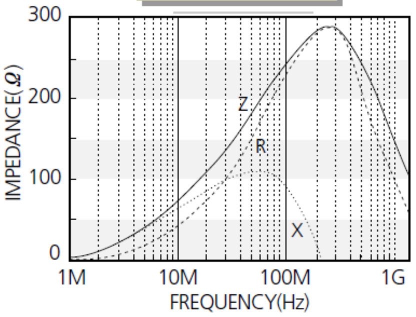

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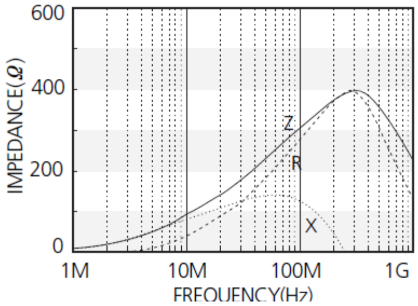

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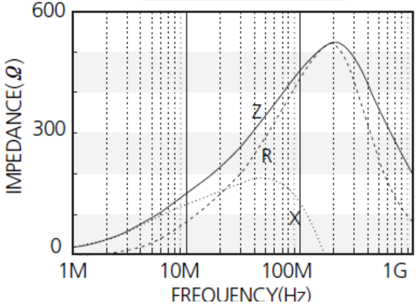

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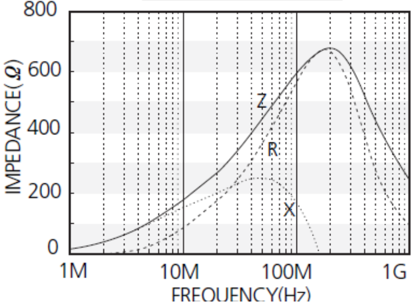

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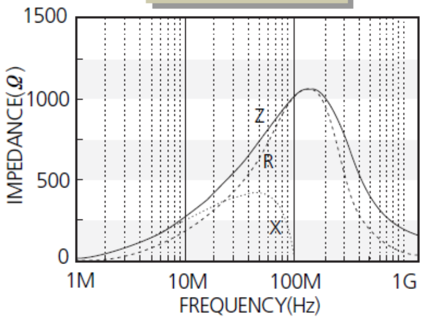

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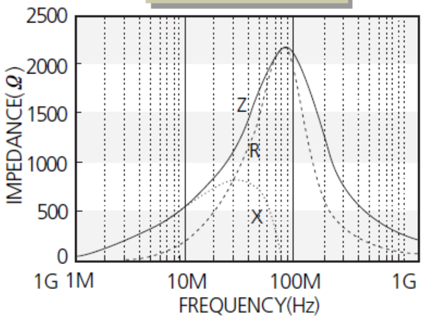

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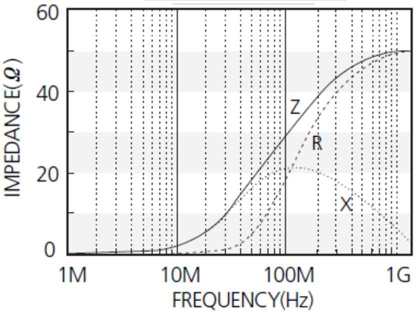

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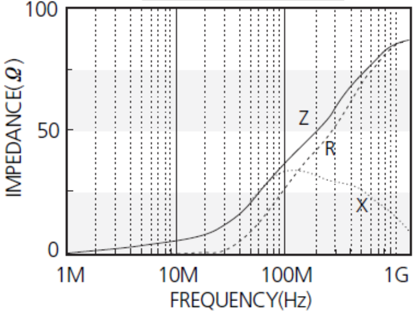

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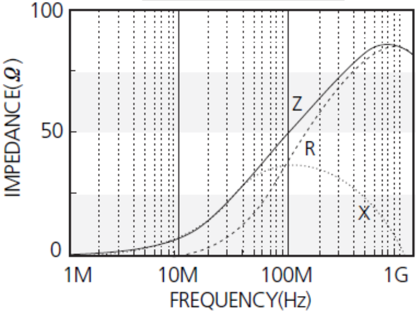

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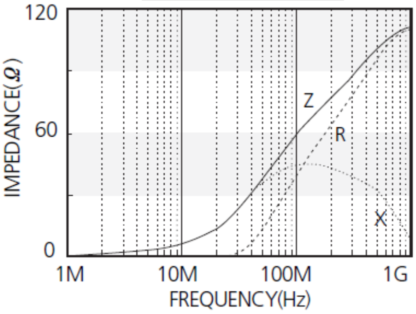

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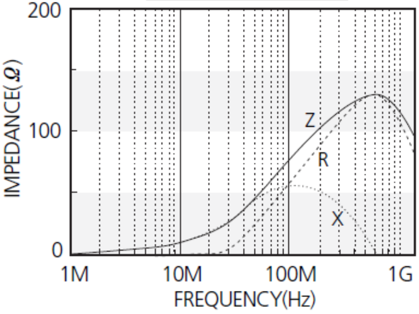

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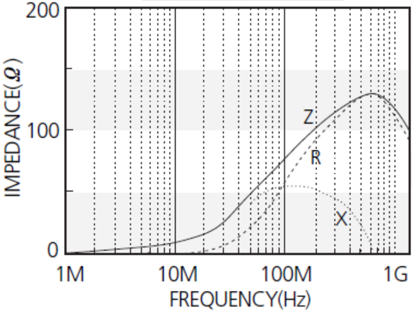

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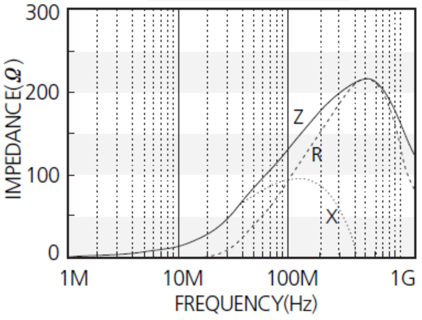

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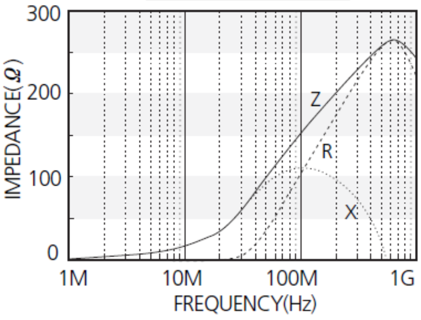

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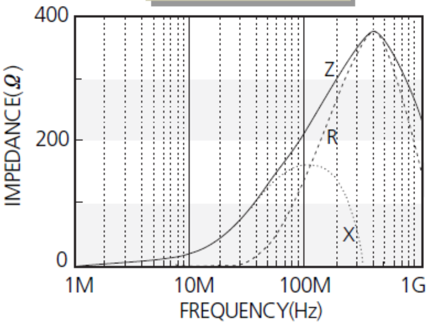

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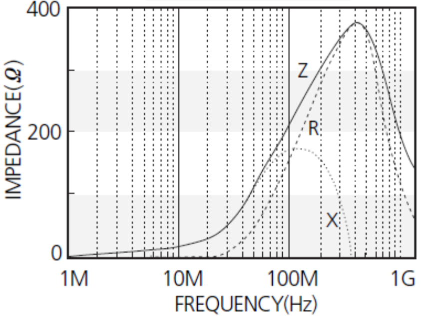

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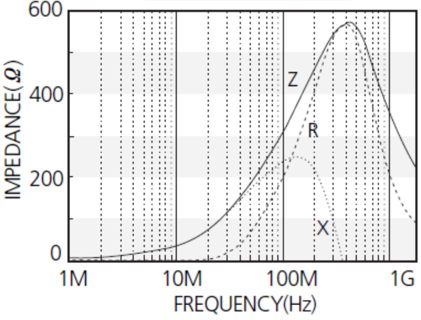

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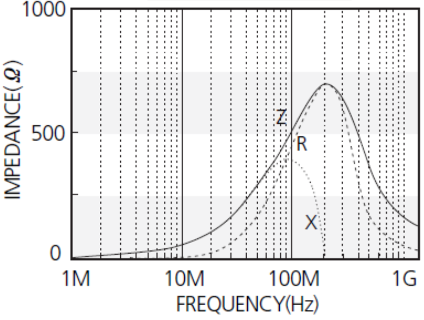

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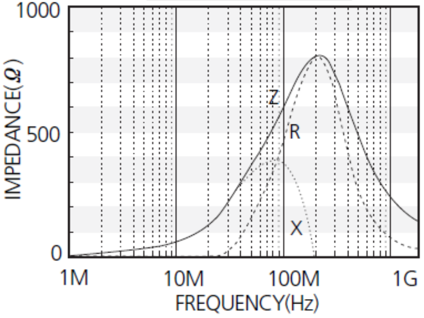

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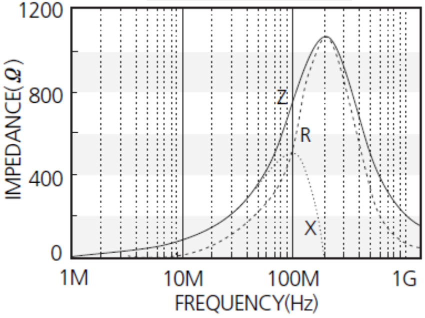

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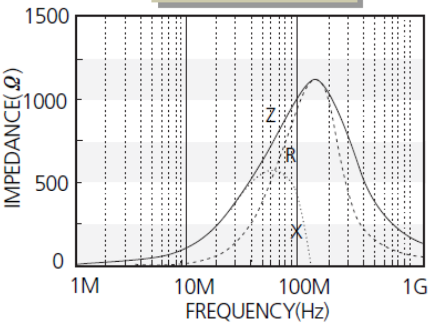

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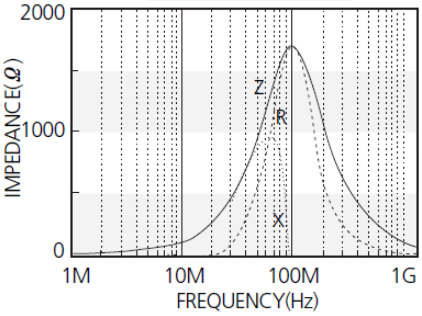

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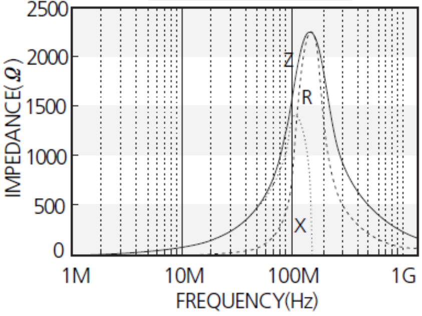

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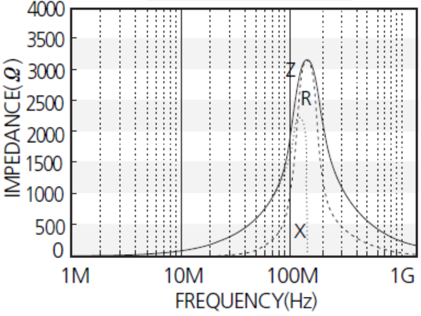

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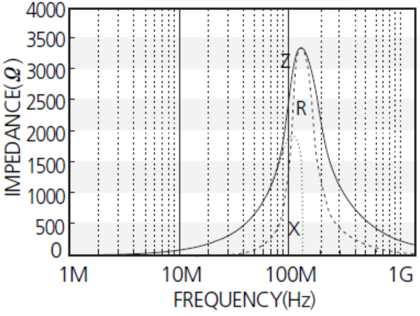

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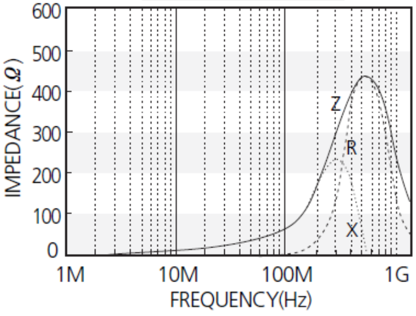

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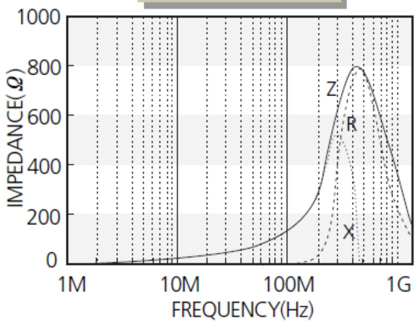

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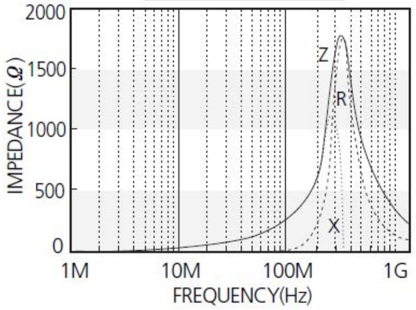

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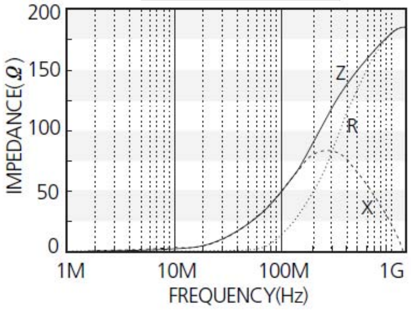

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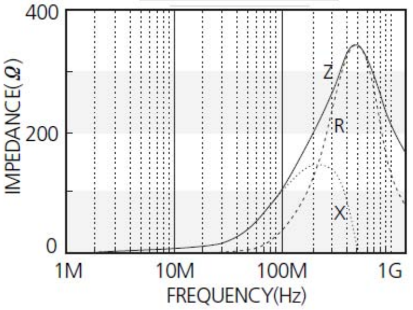


PRODUCT IDENTIFICATION

CI	M	10	U	121	N	C
(1)	(2)	(3)	(4)	(5)	(6)	(7)

(1) Chip Beads

(2) M: Multi-layer type B:Mono-layer type

(3) Dimension

(4) Material Code

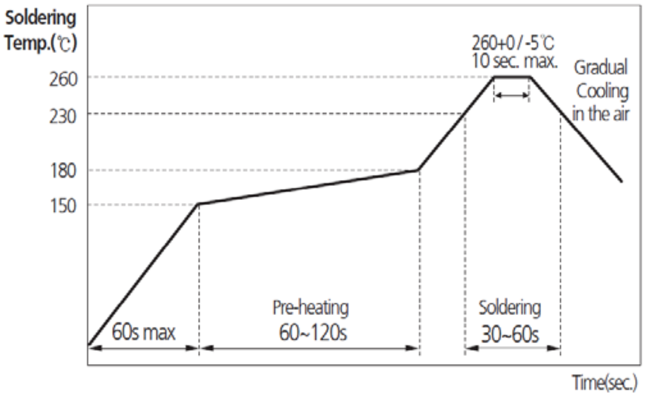
(5) Nominal impedance (121:120Ω, 202:2000Ω)

(6) Thickness option(N:Standard, A:Thinner than standard, B:Thicker than standard)

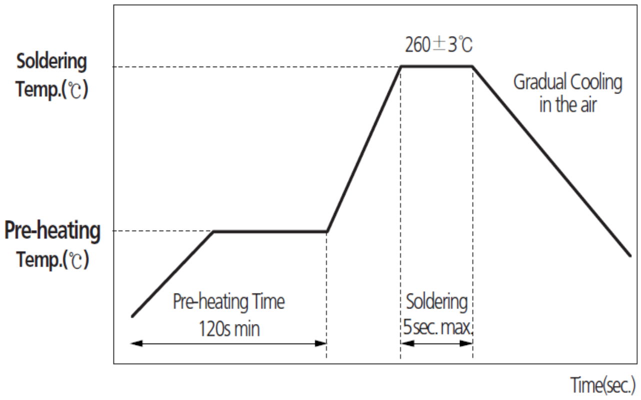
(7) Packaging(C:paper tape, E:embossed tape)

RECOMMENDED SOLDERING CONDITION

REFLOW SOLDERING



FLOW SOLDERING



PACKAGING

Packaging Style	Quantity(pcs/reel)
Card Board Taping	4000

■ NOTICE :All specifications are subject to change without previous notice. Please contact with product representatives or engineers to check specifications.